

SEPARATOR AND SEPARATION METHODABSTRACT OF THE DISCLOSURE

5 A mixture of electronic component chips 2 and media 3 is placed in a planar state on a transport surface 4 of a conveyor 5. Only the media 3 are collected onto a first circulating circumferential surface 18 by a magnetic force provided by a first collection member 12 and are thereafter collected by a media collecting box 22. Then, only electronic component chips 2 having a plating film of a proper thickness formed

10 thereon are absorbed onto a second circumferential surface 28 by a magnetic force provided by a second collection member 23 and are thereafter collected by a good product collecting box 31. Electronic component chips 2a having a plating film of an insufficient thickness formed thereon are collected by a defective product collecting box 32.

attracted

This Sheet Has Been Replaced



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